



S1150G

(UL ANSI: FR-4.1) Halogen-free, Mid-Tg

FEATURES

- Anti-CAF capability
- Lead-free compatible
- Excellent mechanical process ability
- Halogen, antimony and red phosphorous free

APPLICATIONS

Tablet, NB, LED
Smartphone
Game machine
Automotive electronics
Communication equipment

GENERAL PROPERTIES

Test Items		Test Method	Test Condition	Unit	Typical Value
Tg		IPC-TM-650 2.4.25D	DSC	℃	155
Td		IPC-TM-650 2.4.24.6	TGA (5% W.L)	℃	355
T288		IPC-TM-650 2.4.24.1	TMA	min	45
T260		IPC-TM-650 2.4.24.1	TMA	min	>60
Thermal Stress		IPC-TM-650 2.4.13.1	288℃, solder dip	s	>100
CTE (Z-axis)		IPC-TM-650 2.4.24	Before Tg	ppm/℃	40
		IPC-TM-650 2.4.24	After Tg	ppm/℃	230
		IPC-TM-650 2.4.24	50-260℃	%	2.8
Permittivity (1GHz)		IPC-TM-650 2.5.5.9	C-24/23/50	-	4.5
Loss Tangent (1GHz)		IPC-TM-650 2.5.5.9	C-24/23/50	-	0.011
Volume Resistivity		IPC-TM-650 2.5.17.1	C-96/35/90	MΩ-cm	1.15×10 ⁸
Surface Resistivity		IPC-TM-650 2.5.17.1	C-96/35/90	MΩ	9.61×10 ⁶
Arc Resistance		IPC-TM-650 2.5.1	D-48/50+D-0.5/23	s	178
Dielectric Breakdown		IPC-TM-650 2.5.6	D-48/50+D-0.5/23	kV	>45
Peel Strength (1oz)		IPC-TM-650 2.4.8	288℃/10s	N/mm [lb/in]	1.5 [8.57]
Flexural Strength (LW/CW)		IPC-TM-650 2.4.4	A	Mpa	630/480
Water Absorption		IPC-TM-650 2.6.2.1	D-24/23	%	0.10
Flammability		UL94	C-48/23/50	Rating	V-0
Halogen Content	Br	EN 14582	A	ppm	≤900
	Cl				≤900
	Br+Cl				≤1500

Remarks: 1. Specification sheet: IPC-4101/128, is for your reference only.
2. All the typical value is based on the 1.6mm (8*7628) specimen.
3. All the typical value listed above is for your reference only, please turn to Shengyi Technology Co., Ltd for detailed information, and all rights from this data sheet are reserved by Shengyi Technology Co., Ltd.



S1150GB PREPREG

(UL ANSI: FR-4.1) Bonding Prepreg For S1150G

PREPREG PARAMETERS

Glass fabric type	Resin content (%)	Cured thickness (mm)	Standard size (Roll type)
106/1037	73	0.050	1.260m×150m
	75	0.056	
1080/1078	63	0.071	1.260m×300m
	66	0.078	
	68	0.084	
2313	55	0.096	
	57	0.101	
2116	54	0.119	1.260m×250m
	57	0.130	
1506	45	0.152	1.260m×150m
	48	0.163	
7628	43	0.185	
	45	0.195	
	48	0.210	
	50	0.220	

Other type, resin content and size could be available upon request.

HOT PRESSING CYCLE

- The heat-up rate depends on the inner copper or the structure of multilayer PCB.
- Curing time: >45min (180~190℃).
- If you need any more detail information, please turn to Shengyi Technology Co., Ltd.

STORAGE CONDITION

- 3 months when stored at < 23℃ and <50% RH.
- 6 months when stored at <5℃. Normalize in room temperature for at least 4h before using.
- Beware of moisture, always keep wrapped in damp-proof material. Keeping in normal condition, prepreg might absorb moisture and its bonding strength would be weakened.
- Avoid UV-rays and strong light.

PURCHASING INFORMATION

Thickness	Copper foil	Standard size
0.05mm to 3.2mm	12um to 105 um	1,020mm ×1,220mm(40"×48") 915mm ×1,220mm(36"×48") 1,070mm ×1,220mm(42"×48")

Remarks: Other sheet size and thickness could be available upon request.